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- Open-Collector Version of 'BCT244
- Open-Collector Outputs Drive Bus Lines or Buffer Memory Address Registers
- ESD Protection Exceeds 2000 V Per MIL-STD-883C Method 3015
- Packages Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (J, N)

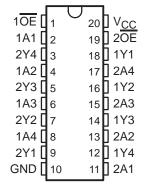
#### description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

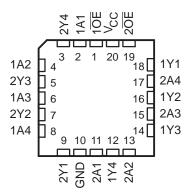
The 'BCT760 is organized as two 4-bit buffers/line drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

The SN54BCT760 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT760 is characterized for operation from 0°C to 70°C.

#### SN54BCT760 . . . J OR W PACKAGE SN74BCT760 . . . DW OR N PACKAGE (TOP VIEW)



# SN54BCT760 . . . FK PACKAGE (TOP VIEW)

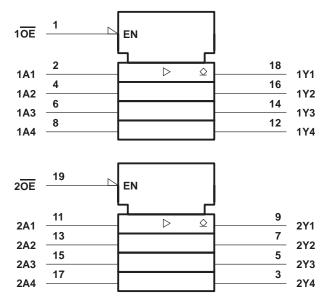


# FUNCTION TABLE (each buffer)

INF	PUTS	OUTPUT			
OE	Α	Υ			
L	Н	Н			
L	L	L			
Н	X	Н			

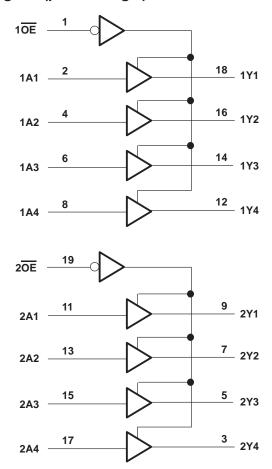
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## logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, Vcc		– 0.5 V to 7 V
,		
Voltage range applied to any output in the	he disabled or power-off state, V <sub>O</sub>	– 0.5 V to 5.5 V
Voltage range applied to any output in the	he high state, VO	– 0.5 V to V <sub>CC</sub>
Current into any output in the low state:	SN54BCT760	96 mÅ
	SN74BCT760	128 mA
Operating free-air temperature range:	SN54BCT760	– 55°C to 125°C
	SN74BCT760	0°C to 70°C
Storage temperature range		– 65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The negative input voltage rating may be exceeded if the input clamp current rating is observed.



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## recommended operating conditions

		SN54BCT760		SN74BCT760			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
Vон	High-level output voltage			5.5			5.5	V
ΙΙΚ	Input clamp current			-18			-18	mA
lOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS			SN	SN54BCT760			SN74BCT760		
PARAMETER		TEST CONDITIONS			TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2			-1.2	V
Vai	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.38	0.55				V
VOL	VCC = 4.5 V	I <sub>OL</sub> = 64 mA					0.42		0.55	V
lį	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.5 V	V <sub>I</sub> = 0.5 V			-1			-1	mA
IOH	$V_{CC} = 4.5 \text{ V},$	V <sub>OH</sub> = 5.5 V				0.1			0.1	mA
			Outputs high		21	33		21	33	
Icc	V <sub>CC</sub> = 5.5 V, Out	Outputs open	Outputs low		48	76		48	76	mA
		OE disable	OE disabled		6	10		6	10	
C <sub>i</sub>	V <sub>C</sub> C = 5 V,	V <sub>I</sub> = 2.5 V or 0.5 V			6			6		pF
Co	V <sub>CC</sub> = 5 V,	$V_{I} = 2.5 \text{ V or } 0.5$	5 V		10			10		pF

 $<sup>\</sup>uparrow$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

# switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	C = 5 V = 50 pF = 500 C = 25°C	<del>-</del> , 2,	C <sub>L</sub> R <sub>L</sub>	= 50 pf = 500 g = MIN t			UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	Any A	Any A	6.3	8	9.5	6.3	11.1	6.3	10	
<sup>t</sup> PHL		Ť	2.1	4.3	6.5	2.1	7.7	2.1	7.2	ns
t <sub>PLH</sub>	ŌĒ	Y	8.6	13	15.2	8.6	18.7	8.6	17.5	ne
t <sub>PHL</sub>	OE .		3.2	6.2	8.9	3.2	10.4	3.2	9.9	ns

<sup>&</sup>lt;sup>‡</sup> For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.







.com 4-Mar-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9093801M2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
5962-9093801MRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
5962-9093801MSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
SN54BCT760J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN74BCT760DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT760DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT760N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74BCT760NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54BCT760FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54BCT760J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SNJ54BCT760W	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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